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**INFORMATION DISCLOSURE  
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Application Number	09/527,931
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First Named Inventor	Gaetan L. Mathieu
Group Art Unit	3726
Examiner Name	Rick K. Chang
Attorney Docket No.	P114-US

**U.S. PUBLISHED PATENT DOCUMENTS**

Examiner Initials*	Cite No. <sup>1</sup>	U.S. Patent Document		Name of Patentee or Applicant	Publ./Issue Date	Related <sup>#</sup>	Copy Enclosed
		Number	Kind Code <sup>2</sup>				
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	2.	7102085		Ohta, et al.	9/2006		No <sup>***</sup>
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Examiner Initials*	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published			T <sup>6</sup>	Copy Enclosed
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	175.	Kai Zoschke et al., “Stackable Thin Film Multi Layer Substrates with Integrated Passive Components”, Electronic Components and Technology Conference-Proceedings, 2006, pages 806-813.				Yes
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OTHER PRIOR ART – NONPATENT LITERATURE DOCUMENTS				
Examiner Initials*	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T <sup>6</sup>	Copy Enclosed
	186.	C. Narayan et al., "Thin Film Transfer for Low Cost MCM-D Fabrication", Proceedings-SPIE, volume 2256, International Conference and Exhibition-Multichip Modules, 1994, pages 105-114.		Yes
	187.	A.J. Piloto et al., "Integrated Passive Components: A Brief Overview of LTCC Surface Mount and Integral Options", proceedings, September 1, 1999, pages 1-7.		Yes
	188.	Karl F. Zimmerman, "SiProbe-A New Technology for Wafer Probing", proceedings, 1995, International Test Conference, pages 106-112 (MJC1975652-58).		Yes
	189.	United States International Trade Commission, In the Matter of Certain Probe Card Assemblies, Components Thereof and Certain Tested DRAM and NAND Flash Memory Devices and Products Containing Same, Inv. No. 337-TA-621, Respondent Micronics Japan Co., LTD's First Supplemental Response to Complainant FormFactor, Inc.'s First Set of Interrogatories (Nos. 25-29), Exhibit 5, March 14, 2008.		Yes
	190.	United States International Trade Commission, In the Matter of Certain Probe Card Assemblies, Components Thereof and Certain Tested DRAM and NAND Flash Memory Devices and Products Containing Same, Investigation No. 337-TA-621, Supplemental Response of Phicom Corporation to Complainant FormFactor, Inc.'s First Set of Interrogatories (Nos. 26-30), Exhibit 29, March 14, 2008		Yes
	191.	"Development of Manufacturing Process Membrane Probe Card", Korean Institute of Machinery and Materials, May 1992		Yes
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Examiner Signature	Date Considered
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\* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication

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\*\* Reference cited in parent application US Serial Nos. 09/527,931. (See 1.98(d).)

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